

## 4<sup>th</sup> United States Low Temperature Plasma Summer School ISPC Summer School ASPIRE Summer School

University of Minnesota, June 14-16, 2025

## Organizers:

Peter J. Bruggeman (University of Minnesota) Satoshi Hamaguchi (Osaka University)

Gerrit Kroesen (TU Eindhoven) Mark J. Kushner (University of Michigan)

The US LTP Summer School will be co-located with the International Symposium on Plasma Chemistry (ISPC) in collaboration with ASPIRE to provide opportunities for graduate students and early career researchers to be immersed in the fundamentals and applications of low-temperature plasmas and to learn from leading researchers in their field. There will be a special session on Plasma Materials Processing (PMP) for Microelectronics Fabrication.

**Registration process:** Please send an expression of interest by filling in the questionnaire: <a href="https://forms.gle/UtQK3ojCTsdaAjw76">https://forms.gle/UtQK3ojCTsdaAjw76</a>.

Registration deadline: April 1st, 2025 or until the maximum number of participants is

reached.

More information: https://z.umn.edu/9wud

Contact: usltpss@umn.edu

Day	Lecture Topics	Confirmed Lecturers
Sat	Introduction to plasma chemistry	Mark Kushner (University of Michigan)
	Plasma sources	Uwe Czarnetzki (Ruhr University Bochum)
	Plasma diagnostics	Igor Adamovich (The Ohio State University, USA)
	Plasma modeling	Juan Pablo Trelles (Uni. of Massachusetts Lowell, USA)
	Materials synthesis	Job Beckers (TU Eindhoven, The Netherlands)
Sun	Track 1: Plasma-liquid interactions	Selma Mededovic Thagard (Clarkson University, USA)
	Thermal plasmas	Tony Murphy (CSIRO, Australia)
	Plasma-surface treatment	Daphne Pappas (Plasmatreat USA, Inc)
	Plasma medicine	Stephan Reuter (Polytechnique Montréal, Canada)
	Plasmas for sustainability	Annemie Bogaerts (University of Antwerp, Belgium)
	Track 2: Plasma-surface interactions	Satoshi Hamaguchi (Osaka University, Japan)
	Atomic Layer Etching	Heeyeop Chae (Sungkyunkwan University (SKKU), Korea.)
	High Aspect Ratio etching	MingMei Wang (Lam Research Corporation, USA)
	Plasma and feature modeling for PMP	Shahid Rauf (Applied Materials, Inc, USA)
	Al and data science in PMP	Tsuyoshi Moriya (Tokyo Electron Techn. Solutions Ltd., Japan)
Мо	Fluorocarbon chemistry & replacements for etch	Pingshan Luan (Tokyo Electron Limited, USA)
	The plasma chemistry of deposition	Nobuyuki Kuboi (Sony Semiconductor Solutions Corp., Japan)
	The chemistry of cryogenic etching	Remi Dussart (GREMI, CNRS/Uni. d'Orléans, France)
	The chemistry of plasma-enhanced ALD	Ageeth Bol (University of Michigan)

Organized with the support of:









